

APPROVAL SHEET

RFBPF Series – 2012(0805)- RoHS Compliance

MULTILAYER CERAMIC BAND PASS FILTER

2.5 GHz Wi-Max Band Working Frequency

P/N: RFBPF20122G5W0T

*Contents in this sheet are subject to change without prior notice.

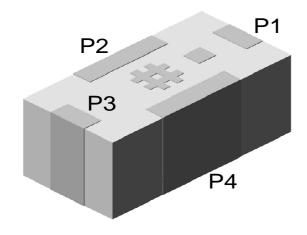
FEATURES

- 1. Miniature footprint: 2.0 X 1.2 X 0.5 mm³
- 2. Low Insertion loss
- 3. Low Profile Thickness
- 4. LTCC process
- 5. High attenuation on 2nd harmonic suppressed

APPLICATIONS

- 1. Wi-Max (Worldwide Interoperability for Microwave Access) RF application.
- 2. Adopt 2.5GHz mobile/ portable design.

CONSTRUCTION



PIN	Connection			
1	Input port			
2	GND			
3	Output port			
4	GND			

DIMENSIONS

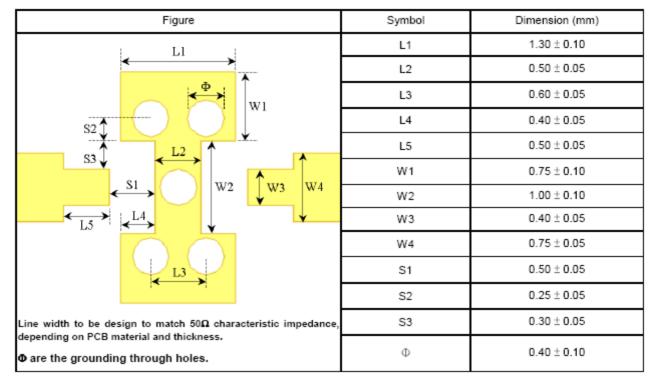
Figure	Symbol	Dimension (mm)
	L	2.00 ± 0.15
# # - 1	W	1.20± 0.15
	Т	0.50 ± 0.10
	А	0.45 ± 0.15
	В	1.10 ± 0.15
	С	0.25 ± 0.15
	D	0.25 ± 0.15
	E	0.45 ± 0.15
	F	0.30 ± 0.15



ELECTRICAL CHARACTERISTICS

RFBPF20122G5W0T	Specification	
Frequency range	2300 - 2690 MHz	
Insertion Loss	2.0 dB max	
VSWR	2.0 max	
Impedance	50 Ω	
Attenuation (min.)	20 dB @ 1600 MHz 30 dB @ 3490 MHz 30 dB @ 4000 MHz 30 dB @ 4490 MHz 30 dB @ 8000 MHz	
Typical Electrical Chart		
0 ((1, 10) -10 -20 -40 -50 -50 1 2	3 4 5 6 7 8 Frequency (GHz)	

SOLDER LAND PATTERN





RELIABILITY TEST

■ Mechanical performance

Test item	Test condition / Test method	Specification
Solderability	*Solder bath temperature : 235 ± 5°C	At least 95% of a surface of each terminal
JIS C 0050-4.6 JESD22-B102D	*Immersion time: 2 ± 0.5 sec	electrode must be covered by fresh solder.
	*Solder : Sn3Ag0.5Cu for lead-free	
Leaching (Resistance to dissolution of metallization) IEC 60068-2-58	*Solder bath temperature : $260 \pm 5^{\circ}\text{C}$ *Leaching immersion time : $30 \pm 0.5 \text{ sec}$ *Solder : SN63A	Loss of metallization on the edges of each electrode shall not exceed 25%.
Resistance to soldering heat JIS C 0050-5.4	*Preheating temperature : 120~150°C, 1 minute. *Solder temperature : 270±5°C *Immersion time : 10±1 sec *Solder : Sn3Ag0.5Cu for lead-free Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Samples shall satisfy electrical specification after test. Loss of metallization on the edges of each electrode shall not exceed 25%.
Drop Test JIS C 0044	*Height: 75 cm *Test Surface: Rigid surface of concrete or steel. *Times: 6 surfaces for each units; 2 times for each side.	No mechanical damage. Samples shall satisfy electrical specification after test.
Adhesive Strength of Termination JIS C 0051- 7.4.3	*Pressurizing force : 5N(≦0603) ; 10N(>0603) *Test time : 10±1 sec	No remarkable damage or removal of the termination.
Bending test JIS C 0051- 7.4.1	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and then pressure shall be maintained for 5±1 sec. Measurement to be made after keeping at room temperature for 24±2 hours	No mechanical damage. Samples shall satisfy electrical specification after test.

Approval sneet		2 Viasin reciniology corporation
Temperature cycle JIS C 0025	 30±3 minutes at -40°C±3°C, 10~15 minutes at room temperature, 30±3 minutes at +85°C±3°C, 10~15 minutes at room temperature, Total 100 continuous cycles Measurement to be made after keeping at room temperature for 24±2 hrs 	No mechanical damage. Samples shall satisfy electrical specification after test.
Vibration JIS C 0040	*Frequency: 10Hz~55Hz~10Hz(1min) *Total amplitude: 1.5mm *Test times: 6hrs.(Two hrs each in three mutually perpendicular directions)	No mechanical damage. Samples shall satisfy electrical specification after test.
High temperature JIS C 0021	*Temperature: 85°C±2°C *Test duration: 1000+24/-0 hours Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Samples shall satisfy electrical specification after test.
Humidity (steady conditions) JIS C 0022	*Humidity: 90% to 95% R.H. *Temperature: 40±2°C *Time: 1000+24/-0 hrs. Measurement to be made after keeping at room temperature for 24±2 hrs % 500hrs measuring the first data then 1000hrs data	No mechanical damage. Samples shall satisfy electrical specification after test.
*Temperature : -40°C±2°C #Test duration : 1000+24/-0 hours Measurement to be made after keeping at room temperature for 24±2 hrs		No mechanical damage. Samples shall satisfy electrical specification after test.

SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,

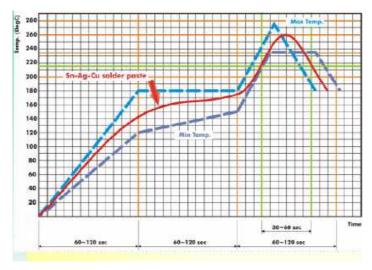


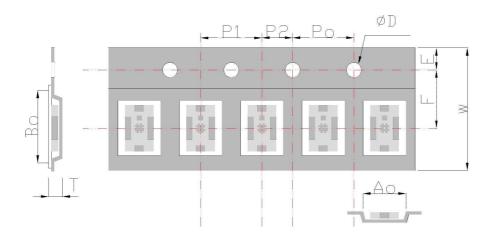
Fig 2. Infrared soldering profile

ORDERING CODE

RF	BPF	2012	2G5	W	0	- T
Walsin	Product	Dimension	Central	Application	Specification	Packing
RF	Code	code	Frequency	W : WiMax	Design Code	T : Reeled
device	BPF:	Per 2 digits of	2G5: 2.5GHz			
	Band	Length, Width,				
	Pass Filter	e.g. 2012 :				
		L= 2.0 mm,				
		W = 1.2 mm,				

Minimum Ordering Quantity: 2000 pcs per reel.

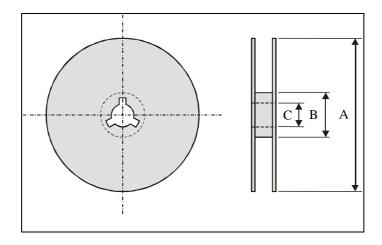
PACKAGING



Plastic Tape specifications (unit :mm)

Index	Ao	Во	ΦD	Т	W
Dimension (mm)	1.45 ± 0.10	2.25 ± 0.10	1.50 ± 0.10	0.64 ± 0.10	8.00 ± 0.10
Index	E	F	Po	P1	P2
Dimension (mm)	1.75 ± 0.10	3.50± 0.05	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.10

Reel dimensions



Index	А	В	С
Dimension (mm)	Ф178.0	Ф60.0	Ф13.0

Taping Quantity:2000 pieces per 7" reel

CAUTION OF HANDLING

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

- Products should be used in 6 months from the day of WALSIN outgoing inspection, which can be confirmed.
- (2) Storage environment condition.
 - Products should be storage in the warehouse on the following conditions.

■ Temperature : -10 to +40°C

Humidity: 30 to 70% relative humidity

- Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
- Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
- Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- Products should be storage under the airtight packaged condition.